

DF3A6.8FUT1

Preferred Device

Zener ESD Protection Diode

Dual Common Anode Zeners for ESD Protection

These dual monolithic silicon zener diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Features

- Pb-Free Package is Available
- SC-70 Package Allows Two Separate Unidirectional Configurations
- Low Leakage < 1.0 μ A @ 5.0 V
- Breakdown Voltage: 6.4–7.2 V @ 5.0 mA
- ESD Protection Meeting: 16 kV Human Body Model
30 kV Contact = IEC61000-4-2
- Peak Power: 24 W @ 1.0 ms (Unidirectional), per Figure 1
- Peak Power: 150 W @ 20 μ s (Unidirectional), per Figure 2

Mechanical Characteristics

- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Steady State Power Dissipation Derate above 25°C (Note 1)	P_D	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	618	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to +150	°C
Peak Power Dissipation @ 1.0 ms (Note 2) @ $T_A = 25^\circ\text{C}$	P_{PK}	20	W
Peak Power Dissipation @ 20 μ s (Note 3) @ $T_A = 25^\circ\text{C}$	P_{PK}	150	W
ESD Discharge MIL STD 883C – Method 3015-6 IEC61000-4-2, Air Discharge IEC61000-4-2, Contact Discharge	V_{PP}	16 30 30	kV

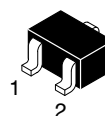
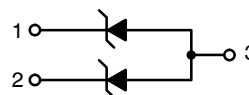
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Mounted on FR-5 Board = 1.0 X 0.75 X 0.062 in.
2. Non-repetitive pulse per Figure 1.
3. Non-repetitive pulse per Figure 2.



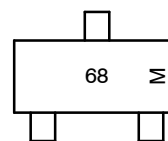
ON Semiconductor®

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SC-70/SOT-323
CASE 419
STYLE 4

MARKING DIAGRAM



68 = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
DF3A6.8FUT1	SC-70	3000/Tape & Reel
DF3A6.8FUT1G	SC-70 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

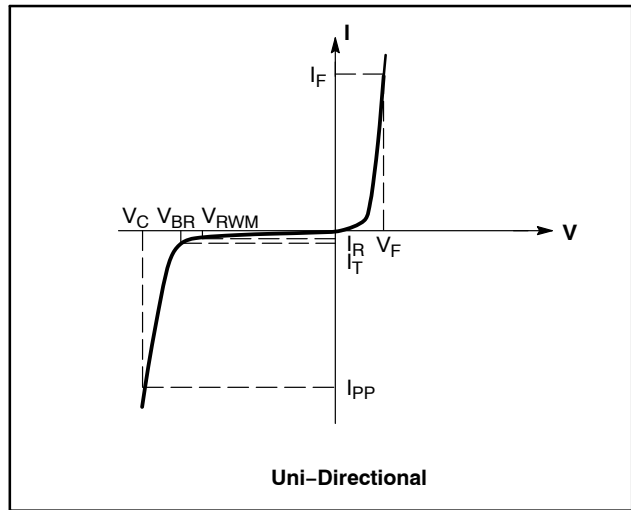
DF3A6.8FUT1

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F
Z_{ZT}	Maximum Zener Impedance @ I_{ZT}
Z_{ZK}	Maximum Zener Impedance @ I_{ZK}



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F = 10 \text{ mA}$		0.8	0.9	V
Zener Voltage (Note 4)	V_Z	$I_{ZT} = 5 \text{ mA}$	6.4	6.8	7.2	V
Operating Resistance (Note 5)	Z_{ZK}	$I_{ZK} = 0.5 \text{ mA}$			200	Ω
	Z_{ZT}	$I_{ZT} = 5 \text{ mA}$			50	Ω
Reverse Current	I_{R1}	$V_{RWM} = 5 \text{ V}$			0.5	μA
Clamping Voltage	V_C	$I_{PP} = 2.0 \text{ A}$ (Figure 1)			9.6	V
		$I_{PP} = 9.37 \text{ A}$ (Figure 2)			16	V
ESD Protection	Human Body Model (HBM) Contact – IEC61000-4-2 Air Discharge				16	kV
					30	
					30	

4. V_Z measured at pulse test current I_{ZT} at an ambient temperature of 25°C .

5. Z_{ZT} and Z_{ZK} is measured by dividing the AC voltage drop across the device by the AC current supplied. AC frequency = 1.0 kHz.

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TYPICAL CHARACTERISTICS

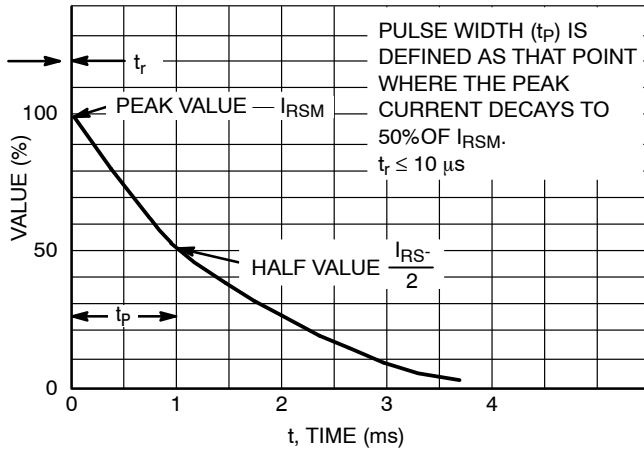


Figure 1. $10 \times 1000 \mu s$ Pulse Waveform

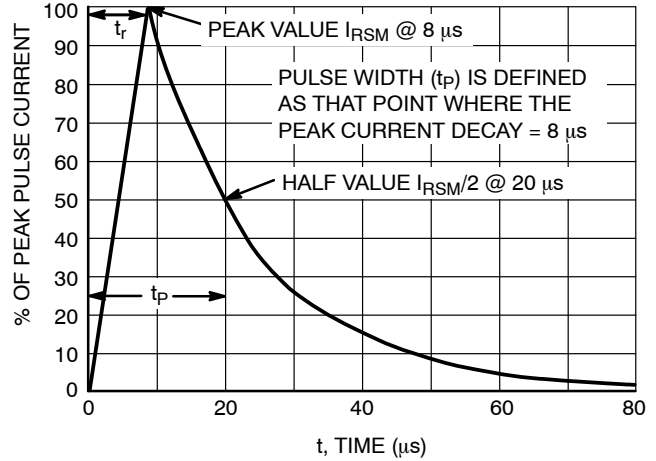


Figure 2. $8 \times 20 \mu s$ Pulse Waveform

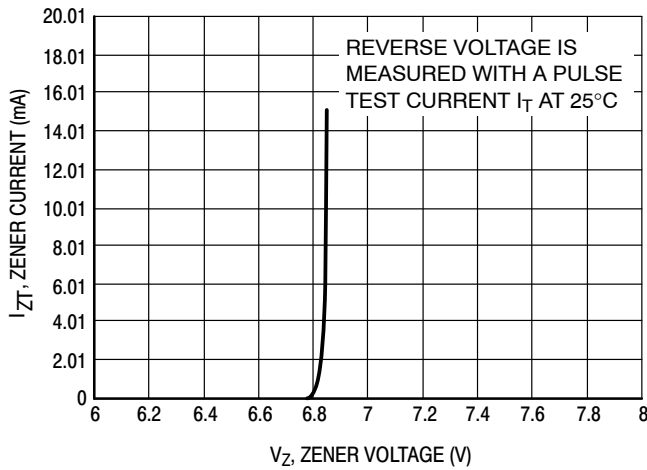


Figure 3. Zener Voltage vs. Zener Current

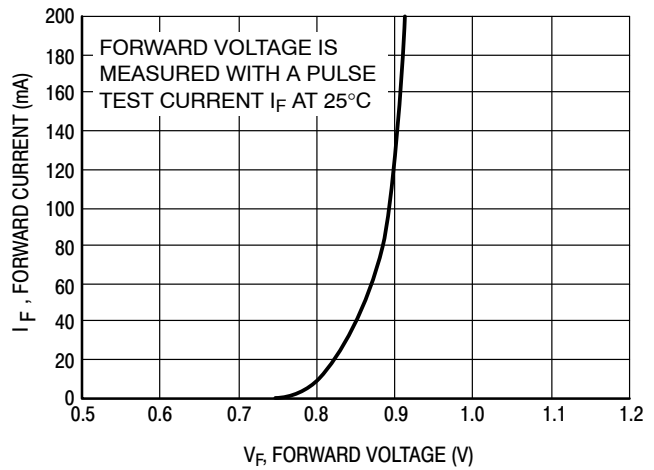


Figure 4. Forward Voltage vs. Forward Current

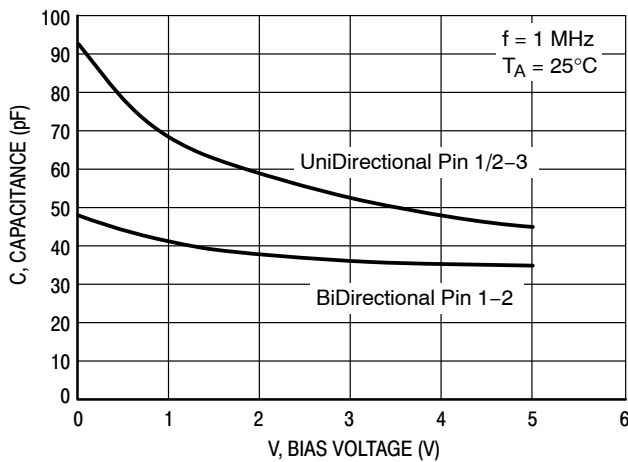


Figure 5. Capacitance vs. Bias Voltage

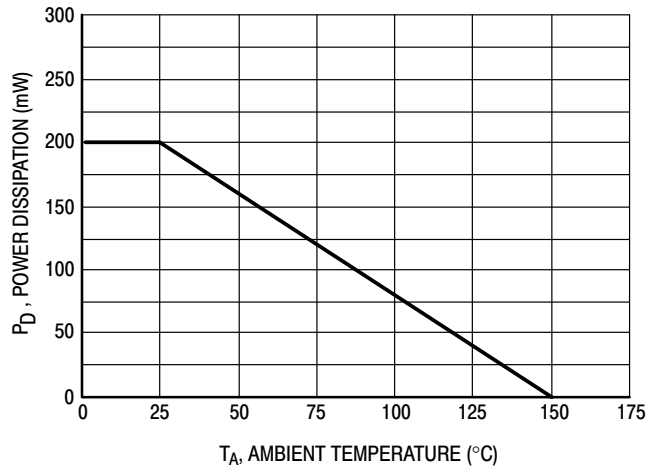
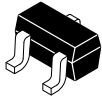


Figure 6. Steady State Power Derating Curve

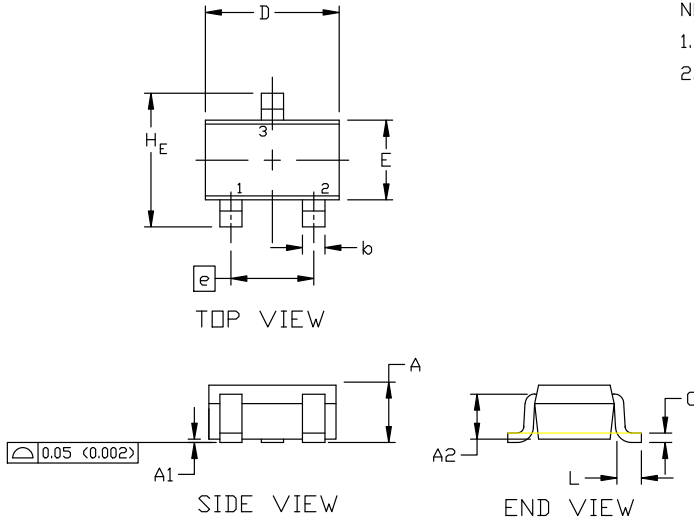
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

SC-70 (SOT-323) CASE 419 ISSUE R

DATE 11 OCT 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

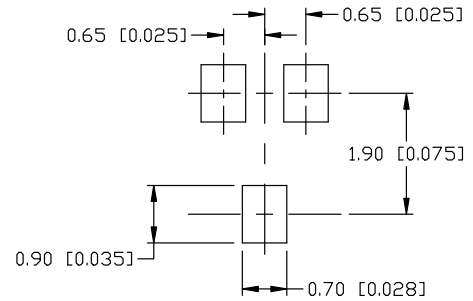
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
H _E	2.00	2.10	2.40	0.079	0.083	0.095

GENERIC MARKING DIAGRAM



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

SOLDERING FOOTPRINT

- | | | | | | |
|---|---|---|--|---|---|
| STYLE 1:
CANCELLED | STYLE 2:
PIN 1. ANODE
2. N.C.
3. CATHODE | STYLE 3:
PIN 1. BASE
2. EMITTER
3. COLLECTOR | STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE | STYLE 5:
PIN 1. ANODE
2. ANODE
3. CATHODE | |
| STYLE 6:
PIN 1. EMITTER
2. BASE
3. COLLECTOR | STYLE 7:
PIN 1. BASE
2. EMITTER
3. COLLECTOR | STYLE 8:
PIN 1. GATE
2. SOURCE
3. DRAIN | STYLE 9:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE | STYLE 10:
PIN 1. CATHODE
2. ANODE
3. ANODE-CATHODE | STYLE 11:
PIN 1. CATHODE
2. CATHODE
3. CATHODE |

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